

HVU131

Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0435-0600
(Previous: ADE-208-239E)
Rev.6.00
Oct 29, 2004

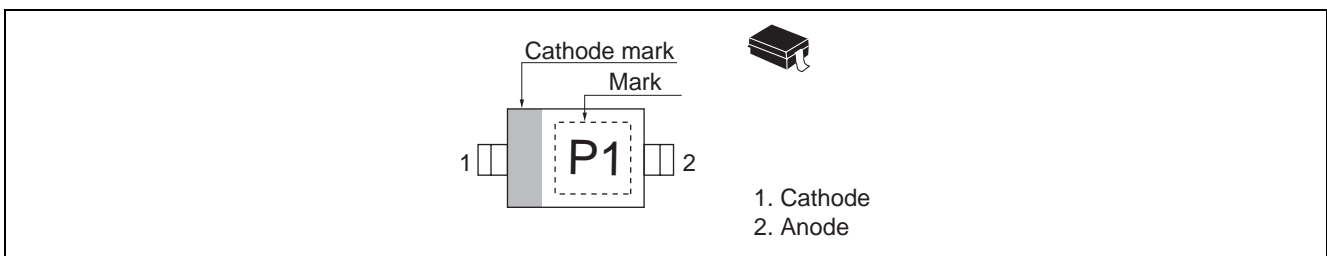
Features

- Low capacitance. ($C = 0.8 \text{ pF max}$)
- Low forward resistance. ($r_f = 1.0 \Omega \text{ max}$)
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVU131	P1	URP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	65	V
Reverse voltage	V_R	60	V
Forward current	I_F	100	mA
Power dissipation	P_d	150	mW
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_R	—	—	0.1	μ A	$V_R = 60$ V
Forward voltage	V_F	—	—	1.0	V	$I_F = 10$ mA
Capacitance	C	—	—	0.8	pF	$V_R = 1$ V, $f = 1$ MHz
Forward resistance	r_f	—	—	1.0	Ω	$I_F = 10$ mA, $f = 100$ MHz

Main Characteristic

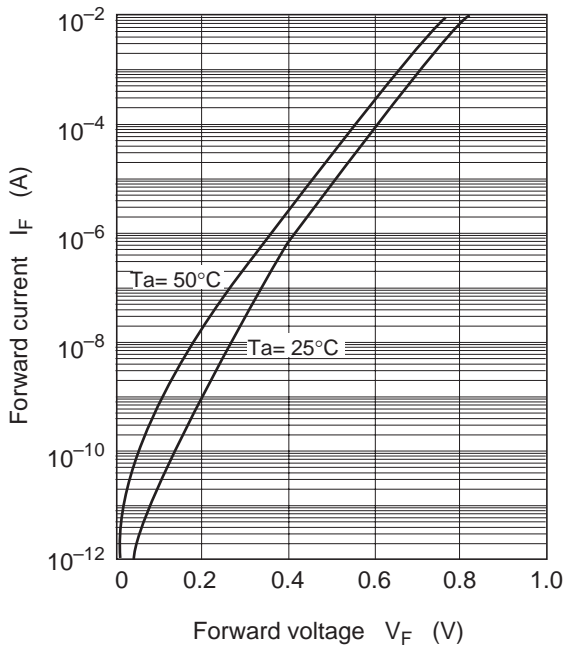


Fig.1 Forward current vs. Forward voltage

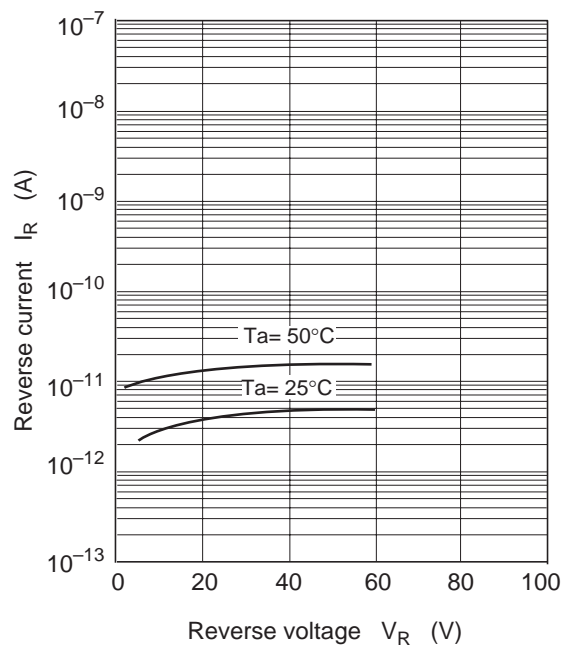


Fig.2 Reverse current vs. Reverse voltage

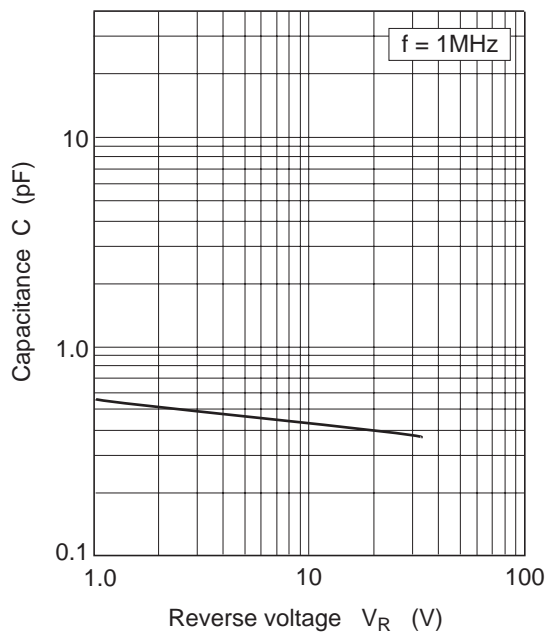


Fig.3 Capacitance vs. Reverse voltage

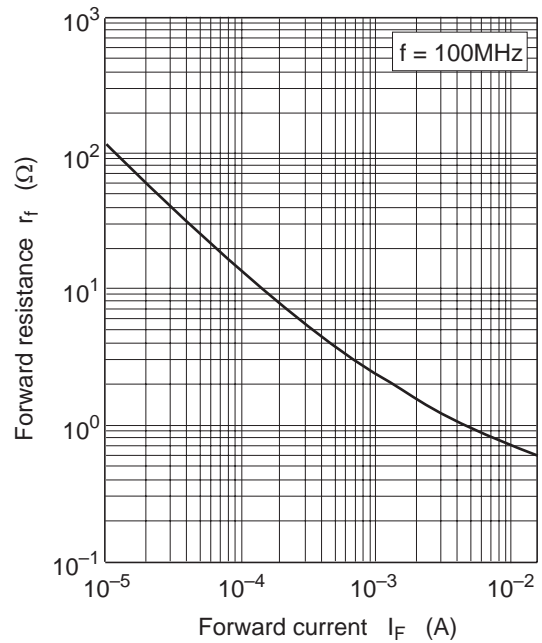
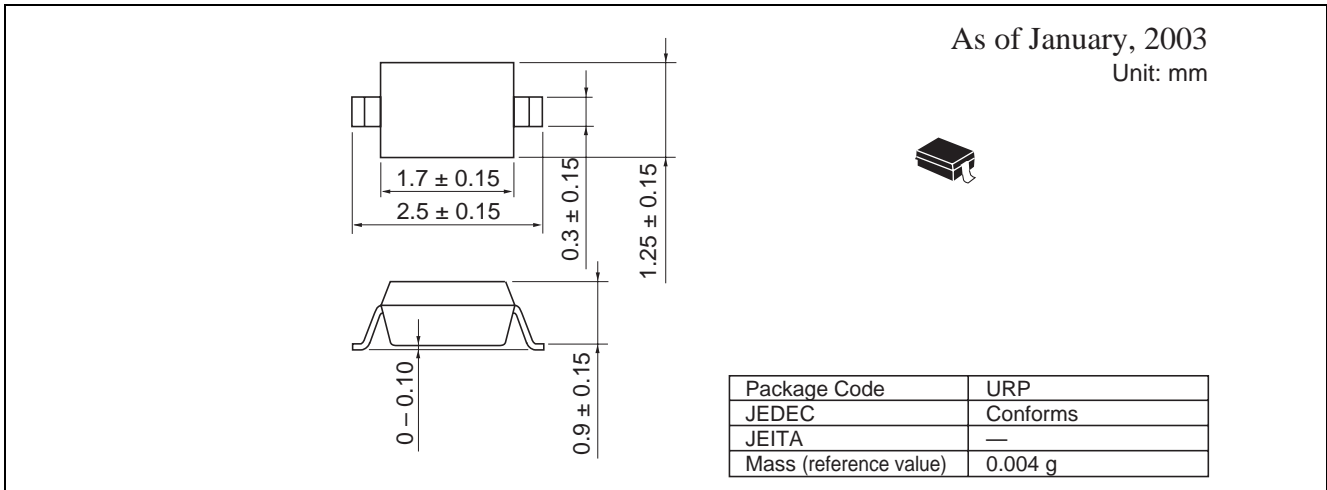


Fig.4 Forward resistance vs. Forward current

Package Dimensions



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